

#### Description

The Si2304BDS-T1-GE3 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub> = 30V I<sub>D</sub> =4A

 $R_{DS(ON)}$  < 38m $\Omega$  @ V<sub>GS</sub>=10V

#### Application

Battery protection

Load switch Uninterruptible power supply

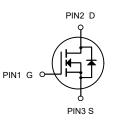
#### Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
Si2304BDS-T1-GE3	SOT-23	HXY MOSFET	3000

#### Absolute Maximum Ratings (T<sub>A</sub>=25<sup>°</sup>C unless otherwise noted)

Symbol	Parameter	Limit	Unit	
VDS	Drain-Source Voltage	30	V	
V <sub>GS</sub>	Gate-Source Voltage	±20	V	
ID	Drain Current-Continuous	4	А	
Ідм	Drain Current-Pulsed (Note 1)	16.4	А	
PD	Maximum Power Dissipation	1	W	
Tj,Tstg	Operating Junction and Storage Temperature Range         -55 To 150		°C	
Reja	Thermal Resistance, Junction-to-Ambient (Note 2)	125	°C/W	





N-Channel MOSFET

N-Channel Enhancement Mode MOSFET



Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA	30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	1.0	1.5	2.5	V
RDS(on)	Static Drain-Source on-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =4A	-	29	38	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A	-	45	65	
Ciss	Input Capacitance		-	233	-	pF
Coss	Output Capacitance	$V_{DS}$ =15V, $V_{GS}$ =0V,	-	44	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	33	-	pF
Qg	Total Gate Charge	- V <sub>DS</sub> =15V, I <sub>D</sub> =2A,	-	3	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	0.5	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge	V <sub>GS</sub> =10V	-	0.8	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time	- V <sub>DS</sub> =15V, - I <sub>D</sub> =4A, R <sub>GEN</sub> =3Ω,	-	4	-	ns
tr	Turn-on Rise Time		-	2.1	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	15	-	ns
t <sub>f</sub>	Turn-off Fall Time	V <sub>GS</sub> =10V	-	3.2	-	ns
ls	Maximum Continuous Drain to Source Diode Forward Current		-	-	4	А
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	16	Α
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =4A	-	-	1.2	V

#### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



# Si2304BDS-T1-GE3 N-Channel Enhancement Mode MOSFET

#### **Typical Characteristics**

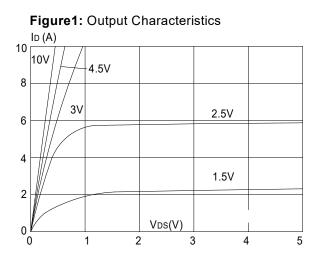
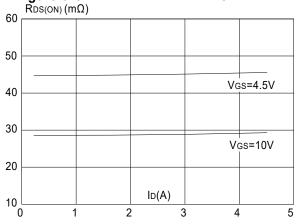
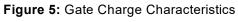
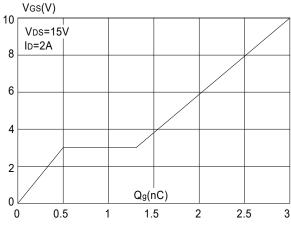
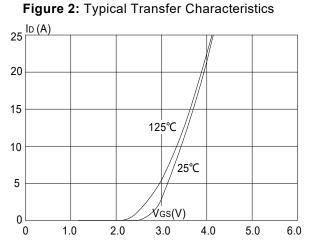


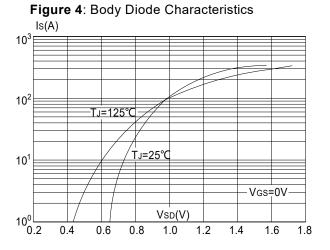
Figure 3:On-resistance vs. Drain Current

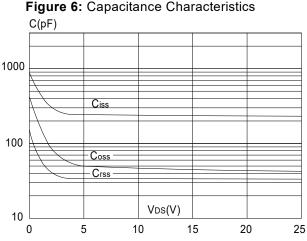












# Figure 6: Capacitance Characteristics



**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature

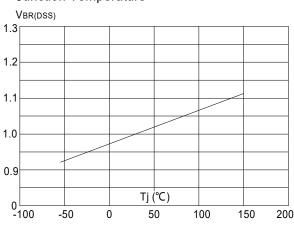


Figure 9: Maximum Safe Operating Area

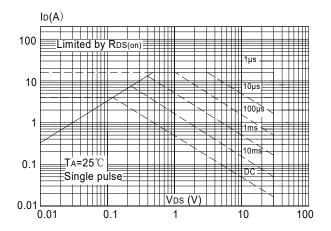
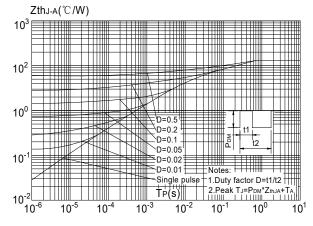
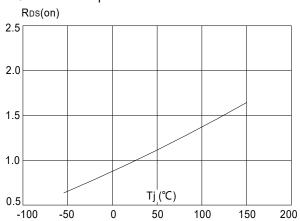


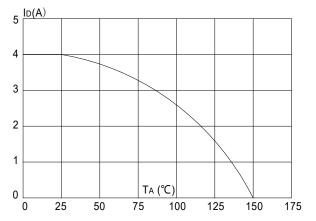
Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



**Figure 8:** Normalized on Resistance vs. Junction Temperature

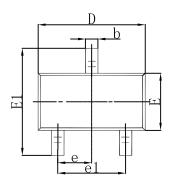


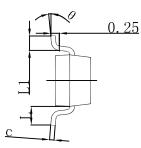
# **Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature

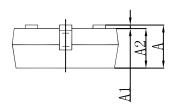




### **SOT-23 Package Outline Dimensions**

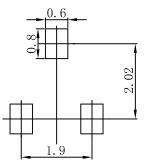






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

## SOT-23 Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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